

Product Change Notification 109212 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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Product Change Notification

Change Notification #: 109212 - 00

Change Title: Intel® X58 Express Chipset, PCN 109212-00,

Product Design, B-2 to B-3 Stepping Change

Date of Publication: February 13, 2009

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Mar 09, 2009 –Mar 20, 2009
Date of Qualification Data Availability:	Feb 13, 2009
Date Customer Must be Ready to Receive Post-Conversion Material:	May 14, 2009
Date of First Availability of Post-Conversion Material:	Apr 10, 2009

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

The IOH component of the Intel® X58 Express chipset is converting from the B-2 stepping to the B-3 stepping. Please plan to validate the B-3 stepping of the Intel® X58 Express chipset. For technical details of the Intel® X58 Express chipset, please refer to the latest Spec Update available on FDBL.

Customer Impact of Change and Recommended Action:

The B-2 stepping of the IOH component of the Intel® X58 Express chipset is pin-to-pin compatible with the B-3 stepping and does not require any motherboard modifications. Design changes, however, have been made to the IOH component of the Intel® X58 Express chipset and will require customers to perform re-qualification. Please see the Intel® X58 Express chipset Spec Update and Intel® X58 Express chipset BIOS Spec Update for any BIOS changes available for the B-3 stepping.

Products Affected / Intel Ordering Codes:

Marketing Name		Pre Conversion S-Spec	Conversion	Stepping	Qualification Samples	Post Conversion Qualification Samples MM#	Post Conversion S-Spec	Conversion	Post Conver. Stepping
Intel® X58 Express Chipset	AC82X58	S LGBT	899355	B-2	QV67	900117	S LGMX	901076	B-3

Reference Documents / Attachments:

Document: Location #:

PCN Revision History:

Date of Revision: Revision Number: Reason:

February 13, 2009 00 Originally Published PCN